1995 International Microwave Symposium

Panel Sessions

(Convention Center/12:00 noon–1:30 pm)

Number	Date/(Room)	Title
PMOA	Monday, May 15, 1995 (Room 12A/B)	Cost Effective MMICs for WLANs: Fact or Fantasy
PTUB	Tuesday, May 16, 1995 (Room 20D)	PHEMTs vs HBTs for Power Amplifiers
PTUC	Tuesday, May 16, 1995 (Room 20E/F/G)	Spectrum Management for Commercial Applications
PWED	Wednesday, May 17, 1995 (Room 20E/F/G)	Microwave Flip Chip Technology

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Rump Session

(Clarion Plaza, Ballroom C/7:00 pm–9:00 pm)

RTUA	Tuesday, May 16, 1995 (Ballroom C)	Microwave Curriculum: What Should We Teach About Microwave Design

Panel Session

PWED: Microwave Flip Chip Technology

Date:	Wednesday, May 17, 1995
Time:	12:00 noon–1:30 pm
Location:	Convention Center, Room 20E,F,G
Sponsors:	MTT-12 Microwave and Millimeter-Wave Packaging MTT-6 Microwave and Millimeter Wave Integrated Circuits
Organizers:	Rick Sturdivant, TRW Transportation and Electronics Division Tim Kemerley, Wright Laboratory, WPAFB
Moderator:	Rick Sturdivant, TRW Transportation and Electronics Division
Panelists:	John Bugeau, Lockheed Sanders Dev Gupta, Motorola Karl Puttlitz, IBM Hiroya Sato, Sharp Corp. R. Hahn, Univ. of Berlin, Germany Randy Turnage, H.E. Microwave Darren Walworth, GM Hughes Electronics

Abstract:

Microwave flip chip technology is attractive for low cost, high volume applications such as PCN, wireless and radar. This technology reduces processing cost, and offers low cost attachment and interconnect, and high reliability. Although this technology is being used and proposed for use in a variety of applications, little is being published about it. Therefore, pressing need exists for an overview of a few of the current applications and the central issues relating to the use of microwave flip chips. This panel session will focus on current applications and the enabling technology, which permits the use of microwave flip chips.